

NTD280N60S5Z-VB Datasheet

N-Channel 600V (D-S) Super Junction Power MOSFET

PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	600				
R _{DS(on)} typ. (Ω) at 25 °C	V _{GS} = 10 V	0.240			

FEATURES

- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Qg)
- Avalanche energy rated (UIS)

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

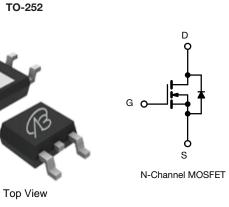
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V _{DS}	600	V	
Gate-source voltage			V _{GS}	± 30	V	
Continuous drain current ($T_J = 150 \ ^\circ C$)	V _{GS} at 10 V	$T_{\rm C} = 25 \ ^{\circ}{\rm C}$ $T_{\rm C} = 100 \ ^{\circ}{\rm C}$	- I _D	15		
	VGS at 10 V	T _C = 100 °C		12	А	
Pulsed drain current ^a			I _{DM}	45		
Linear derating factor				1.7	W/°C	
Single pulse avalanche energy ^b			E _{AS}	320	mJ	
Maximum power dissipation			PD	180	W	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C	
Drain-source voltage slope	$T_J = T_J$	125 °C	d\//dt	50	V/ns	
Reverse diode dV/dt ^d			dV/dt	5.1	v/ns	
Soldering recommendations (peak temperature)	For 10 s			260	°C	

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature

- b. V_{DD} = 100 V, starting T_J = 25 °C, L = 30 mH, R_g = 25 $\Omega,\,I_{AS}$ = 7 A
- c. 1.6 mm from case
- d. $I_{SD} \leq I_D$, dl/dt = 100 A/µs, starting T_J = 25 °C





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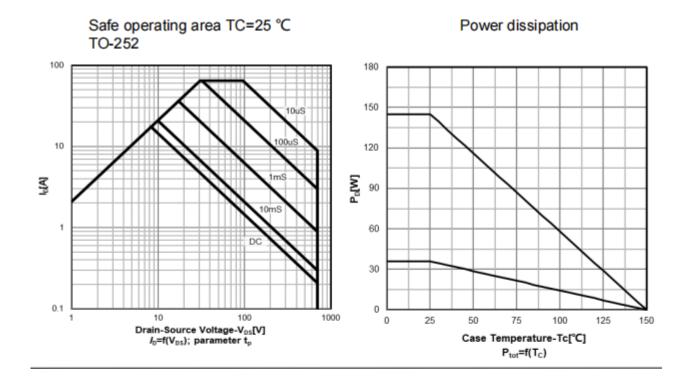
THERMAL RESISTANCE RATI	NGS								
PARAMETER	SYMBOL	TYP.		MAX.		UNIT			
Maximum junction-to-ambient	R _{thJA}	- 62				°C/W			
Maximum junction-to-case (drain)	R _{thJC}	- 0.85				- C/W			
SPECIFICATIONS (T_J = 25 °C, ι	inless otherwi	se noted)							
PARAMETER	SYMBOL	TES	T CONDIT	IONS	MIN.	TYP.	MAX.	UNIT	
Static									
Drain-source breakdown voltage	V _{DS}	V _{GS} =	0 V, I _D = 2	250 µA	600	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C,	$I_D = 1 \text{ mA}$	-	1.08	-	V/°C	
Gate-source threshold Voltage (N)	V _{GS(th)}	V _{DS} =	$= V_{GS}, I_D =$	250 µA	2.0	-	4.0	V	
Onto any lands and	I _{GSS}	$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA		
Gate-source leakage		$V_{GS} = \pm 30 \text{ V}$		-	-	± 1	μA		
		V _{DS} =	= 600 V, V _C	_{as} = 0 V	-	-	1		
Zero gate voltage drain current	I _{DSS}	V _{DS} = 480 V, V _{GS} = 0 V, T _J = 125 °C		√, T _J = 125 °C	-	-	10	μA	
Drain-source on-state resistance	R _{DS(on)}	$V_{GS} = 10 V$		_D =5 A	-	0.240	-	Ω	
Forward transconductance	9 _{fs}	V _{DS}	= 30 V, I _D :	= 15 A	-	8.7	-	S	
Dynamic					•	•			
Input capacitance	C _{iss}	$V_{GS} = 0 V,$ $V_{DS} = 100 V,$ f = 1 MHz		-	1900	-	pF		
Output capacitance	C _{oss}			-	51	-			
Reverse transfer capacitance	C _{rss}			-	12	-			
Effective output capacitance, energy related ^a	C _{o(er)}	$V_{DS} = 0$ V to 480 V, $V_{GS} = 0$ V		-	50	-			
Effective output capacitance, time related ^b	C _{o(tr)}			-	205	-			
Total gate charge	Qg	V _{GS} = 10 V I _D = 15 A, V _{DS} = 480 V		-	25	-	nC		
Gate-source charge	Q _{gs}			-	8	-			
Gate-drain charge	Q _{gd}				-	10	-	1	
Turn-on delay time	t _{d(on)}				-	12	24		
Rise time	t _r	$V_{DD} = 480 \text{ V}, \text{ I}_{D} = 15 \text{ A},$ $V_{GS} = 10 \text{ V}, \text{ R}_{g} = 9.1 \Omega$ f = 1 MHz, open drain		-	14	23	ns		
Turn-off delay time	t _{d(off)}			-	61	110			
Fall time	t _f			-	16	-			
Gate input resistance	R _g			0.3	0.7	1.4	Ω		
Drain-Source Body Diode Characteristic									
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	20			
Pulsed diode forward current	I _{SM}			-	-	60	A		
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 15 A, V _{GS} = 0 V		-	-	1.2	V		
Reverse recovery time	t _{rr}				-	85	90	ns	
Reverse recovery charge	Q _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 15 \text{ A},$ dI/dt = 100 A/µs, V _R = 25 V		-	6.4	12.8	μC		
Reverse recovery current	I _{RRM}			-	27	-	A		

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}

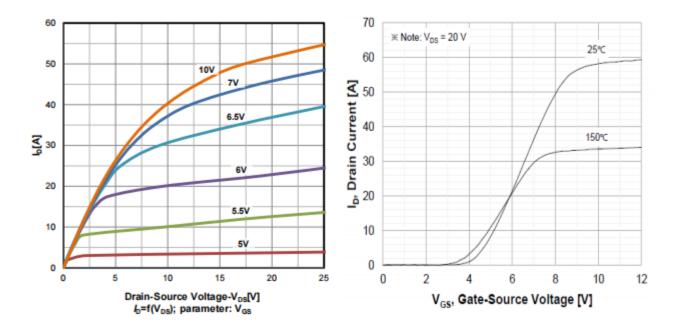


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Typ. output characteristics $T_i=25 \ ^{\circ}C$

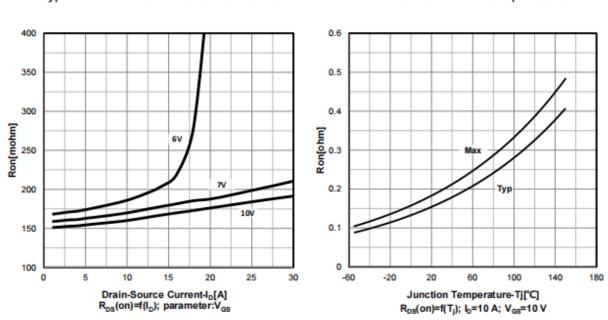
Transfer characteristics



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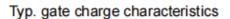


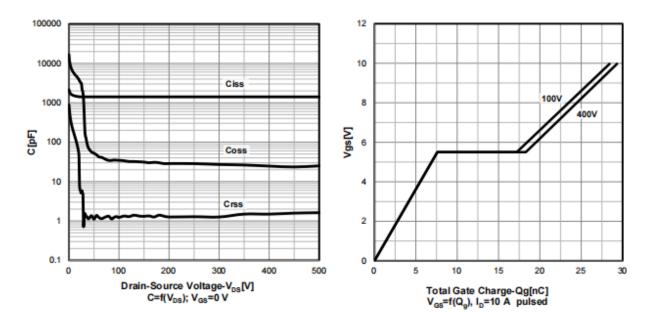


Typ. drain-source on-state resistance

On-resistance vs temperature

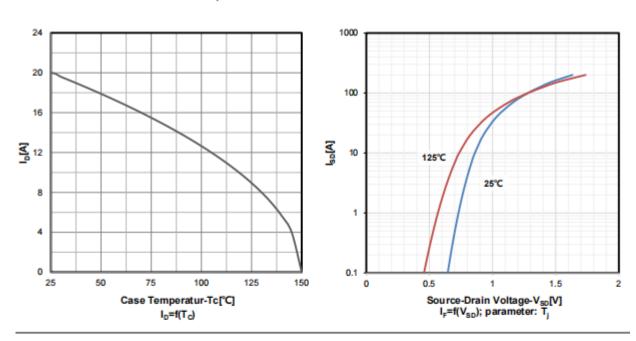
Typ. capacitances





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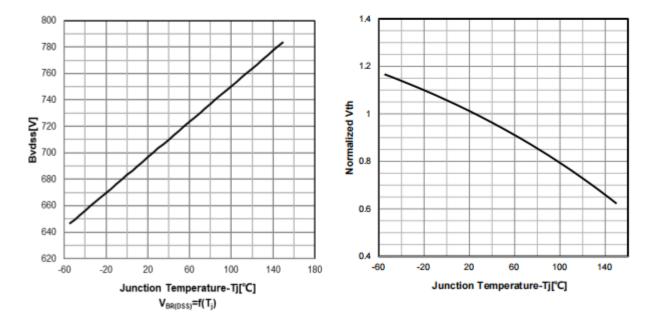


Drain current vs temperature

Forward characteristics of reverse diode

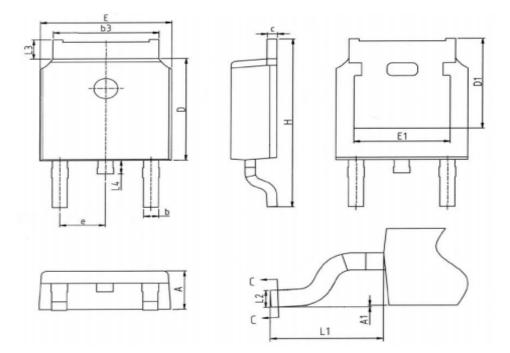
Drain-source breakdown voltage

Normalized VGS(th) characteristics





Package Outline : TO 252



COMMON DIMENSIONS

SYMBOL	UNIT(mm)				
SIMBOL	MIN	NOM	MAX		
A	2.20	2.30	2.40		
A1	0.00	-	0.127		
b	0.66	0.78	0.90		
b3	5.16	5.31	5.46		
с	0.43	0.53	0.63		
D	5.98	6.10	6.22		
D1	5.30REF				
E	6.40	6.60	6.75		
E1	4.63	-	-		
е	2.286BSC				
H	9.40	10.10	10.50		
L1	2.90REF				
L2	0.51BSC				
L3	0.88	1.08	1.28		
L4	0.50	0.80	1.00		



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